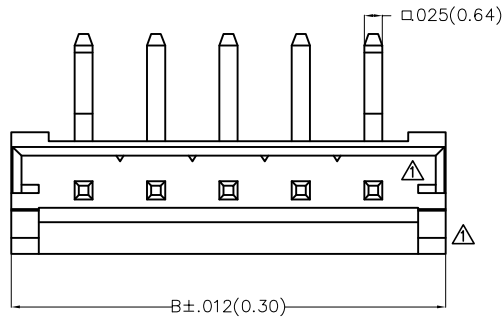


1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Update structure and dimensions	03/NOV/22	MATT	CHERRY
2	△	Update dimensions and tolerances	19/SEP/24	MATT	CHERRY

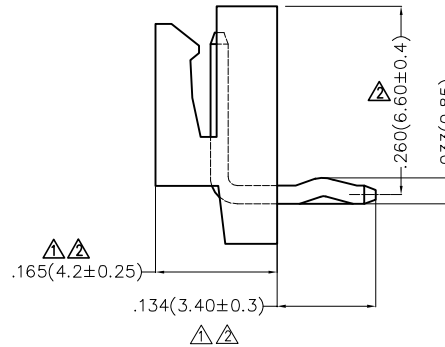
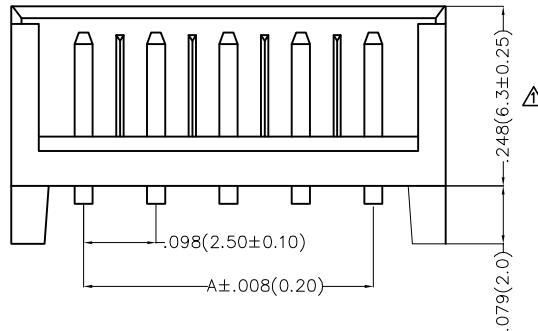


**Electrical**

Current Rating: 3.0A AC(rms)/DC  
 Voltage Rating: 250V AC(rms)/DC  
 Contact Resistance: 20 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 800V AC r.m.s  
 Temperature Range—Operating: -25°C~+85°C

**Material and Plating**

Housing: PA66( UL 94V-0)  
 Contact Pin: Brass  
 Plating: Tin Plated

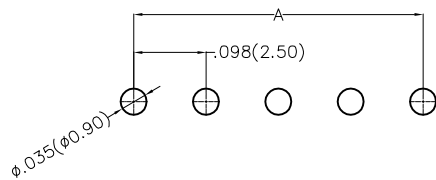


Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B △△
2	FWF25006-S02B22W1B	.098(2.50)	.295(7.50)
3	FWF25006-S03B22W1B	.197(5.00)	.394(10.00)
4	FWF25006-S04B22W1B	.295(7.50)	.492(12.50)
5	FWF25006-S05B22W1B	.394(10.00)	.591(15.00)
6	FWF25006-S06B22W1B	.492(12.50)	.689(17.50)
7	FWF25006-S07B22W1B	.591(15.00)	.787(20.00)
8	FWF25006-S08B22W1B	.689(17.50)	.886(22.50)
9	FWF25006-S09B22W1B	.787(20.00)	.984(25.00)

**Ordering Information**

FWF 250 06 — S XX B 2 2 W1 B  
 1 2 3 4 5 6 7 8 9 10

1   Category FWF-Wafer	2   Series Number 250-Pitch2.5mm	3   Distinction No. 06	4   Row Option S-Single Row	5   Circuits XX	6   Entry Angle B-90° Angle
7   Plating 2-Tin Plated	8   Material-Resin 2-PA66	9   Color-Resin W1-White	10   Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone
DESIGN UNITS Inch (metric)	X.±.012(0.30)	X:±5°		FRANK	01/JUL/13	FWF25006-SXXB22W1B	FWF25006	
	X.XX±.008(0.20)	.XX±2'		CHECKED BY	DATE	TITLE		
	X.XX±.006(0.15)	.XX±1'		JACOB	01/JUL/13	Wire to Board (Wafer) Pitch 2.5mm 90° Angle( DIP)		REV 2 SHEET NO. 1/1
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				CHERRY	01/JUL/13			

1 2 3 4 5 6 7 8